投資人議合數據	法人說明會	實體會議	媒體報導
2026 年次數	3	6	18
歷年次數	3	6	18

註：資料截至 2026/10/23

本公司定期參加法人說明會，說明營運成果、財務狀況及未來展望，並於會中針對投資人現場提問進行回覆與紀錄，法說會簡報與會議影音已公開揭露於公司網站之「投資人關係」專區，確保資訊透明，115 年度法說會中投資人關切議題及公司之回應重點摘要如下：

Q1：半導體及先進封裝產品比重提升，是否有助於公司毛利率成長？

應用於半導體製程的 ICP-RIE 設備及載板製程的連續式電漿設備，均為公司毛利率表現較佳的產品。隨高階設備出貨比重提升及自動化功能導入，公司對明年度整體毛利率表現持審慎樂觀看法。

Q2：公司的乾式電漿技術是否可完全取代雷射進行 TGV 玻璃鑽孔？

現階段 TGV 通孔仍主要採用雷射搭配化學方式形成。公司的電漿技術主要應用於通孔形成後的孔壁粗化、表面改質及殘留物清潔，以提升後續鍍銅附著效果並降低玻璃裂損風險。

Q3：電漿製程在何種孔徑下較雷射鑽孔具技術優勢？

依公司目前與客戶合作及測試經驗，當孔徑縮小至約 20 微米以下時，電漿製程的技術優勢逐漸顯現。公司目前正與國內大型 IC 載板廠進行製程開發，並持續改善量產效率及良率。

Q4：現有產能及委外工廠是否足以支應後續訂單？

依目前在手訂單及預估的明年度訂單，現有產能與委外合作模式尚可支應。若未來取得大批量標準設備訂單，合作的衛星工廠將協助公司擴充產能及縮短交期。

Investor Engagement Data	Investor Conferences	In-person Meetings	Media Coverage
2026 Count	3	6	18
Cumulative Count	3	6	18

Note: Data as of October 23, 2026

NEMStek regularly participates in investor conferences to present its operating results, financial position, and future outlook. During these conferences, the Company responds to and records questions raised by investors. Investor conference presentation materials and video recordings are publicly available in the Investor Relations section of the Company's website to ensure information transparency. A summary of the key issues raised by investors and the Company's responses at its 2026 investor conferences is provided below:

Q1: As the proportion of semiconductor and advanced packaging products increases, will this contribute to growth in the Company's gross margin?

ICP-RIE systems used in semiconductor manufacturing and In-line Plasma systems used in IC substrate production are among the Company's higher-margin products. As the share of high-end equipment shipments increases and automation functions are introduced, the Company remains cautiously optimistic about its overall gross margin performance next year.

Q2: Can the Company's dry plasma technology completely replace laser drilling for TGV glass vias?

At present, TGV through-holes are still primarily formed using a combination of laser and chemical processes. The Company's plasma technology is mainly applied after via formation for sidewall roughening, surface modification, and residue cleaning, thereby improving copper

plating adhesion and reducing the risk of glass cracking.

Q3: At what via diameter does the plasma process have a technical advantage over laser drilling?

Based on the Company’ s current customer collaboration and testing experience, the technical advantages of plasma processing become increasingly apparent when the via diameter is reduced to approximately 20 μm or less. The Company is currently conducting process development with a major domestic IC substrate manufacturer and continues to improve mass-production efficiency and yield.

Q4: Are the Company’ s existing capacity and outsourced manufacturing partners sufficient to support future orders?

Based on current orders on hand and projected orders for next year, existing capacity and the outsourced manufacturing model remain sufficient. If the Company receives large-volume orders for standard equipment in the future, its partner satellite factories will assist in expanding capacity and shortening lead times.